Microelectronics Technology S 2024 Crib Sheet Exam 1+2 Hayden Fuller

n-type, majority e minority h, donors, 5 electron, P, As, Sb, p-type, majority h minority e, acceptors, 3 electron, B, Al, Ga, In  $p_n$  holes in n side, minority

 $1eV=1.6\times 10^{-19}J$ 

 $k = 1.38 \times 10^{-23} J/K = 8.6 \times 10^{-5} eV/K$  , kT = 0.025 eV

 $E_{G Si} = 1.12 eV$ 

 $n_i = 10^{10}$ ,  $n_i^2 = np$ ,  $n = n_i e^{(E_F - E_i)/kT}$ ,  $p = n_i e^{(E_i - E_F)/kT}$ 

 $p - n + N_D - N_A = 0$ ,  $n^2 - n(N_D - N_A) - n_i^2 = 0$ 

 $N_D > N_A = > n = N_D - N_A ; p = n_i^2/n N_D \approx N_A = > n = p = n_i$ 

Band diagrams: n-type:  $E_C, E_F, E_i, E_v$ , p-type:  $E_C, E_i, E_F, E_v$ 

Point defect: one atom missing. Electron generation: one electron missing

Electron moving: breaks off and moves. Hole moving: electron line rotates into hole.

effective mass:

Fermi function  $f(E) = \frac{1}{1+e^{(E-E_F)/kT}}$ , Steps from 1 to 0 at  $E_F$  at 0K, smoothe at temp.

 $E_F = 1 - e^{\frac{E - E_F}{kT}} = \frac{E_C + E_V}{2}$  in intrinsic

Distribution of carriers = distribution of states \* probability of occupancy = g(E)f(E)Conduction band electrons:  $n_0 = \int_{E_C}^{E_t op} g_C(E)f(E)dE$ , holes in VB:  $p_0 = \int_{E_b ottom}^{E_v} g_V(E)(1 - f(E))dE$ 

total free electron concentration 3kT away from edges (non-degenerate):  $n=N_c e^{-\frac{E_C-E_F}{kT}}$ , hole:  $p=N_v e^{-\frac{E_F-E_V}{kT}}$ where effective density of states  $N_C = 2.8 \times 10^{19} cm^{-3}$  and  $N_C = 1 \times 10^{19} cm^{-3}$ , 3kT around  $N_{AorD} = 2 \times 10^{17} cm^{-3}$ 

Drift: caused by electric field, drift velocity  $v_d = \mu_p E \ cm/sec = cm^2/Vs*V/cm$ 

I = Q/T,  $J_{P|drift} = I/A = qp\mu_p E = \frac{E}{q}$ 

resistivity:  $\rho = 1/(1p\mu_p + qn\mu_n)$ 

resistivity measurement: 4 point probe, eddy current apparatus

Diffusion: random thermal mothion, high to low concentration, must be a concentration gradient

Flux  $F = -D\frac{d\eta}{dx}$ ,  $\eta = \text{particle concentration}$ , D = diffusion coefficient

holes/electrons go high to low, that's flux, but diffusion current is negative for electrons  $J_{p|diff} = -qD_p\frac{dp}{dx}\,,\ J_{n|diff} = qD_n\frac{dn}{dx}$ 

 $J_p = J_{p|drift} + J_{p|diff} = q\mu_p pE + -qD_p \frac{dp}{dx} \; , \; J_n = J_{n|drift} + J_{n|diff} = q\mu_n nE + qD_n \frac{dn}{dx} \; , \; J = J_n + J_p$  Band bending: electric field bends the band diagram

$$KE = E - E_C$$
,  $PE = E_C - E_{ref} = -qV$  (for electrons),  $V = -(E_C - E_{ref})/q$ ,  $E = -\frac{dV}{dx} = \frac{dE_{C,V,i}}{dx}/q$ 

Hot point measurement: Hot end makes particles move away.

p-type: holes move away, current goes out hot probe. n-type: electrons move away, current goes into hot probe in thermal equilibrium:  $E_F$  is constant, net current  $J_{p|drift} + J_{p|diff} = 0$ , recombination and generation cancel

Einstein:  $J_{n|drift} + J_{n|diff} = q\mu_n nE + qD_n \frac{dn}{dx} = 0$ ,  $E = \frac{dE_i}{dx}/q$ ,  $n = n_i e^{(E_F - E_i)/kT}$  electrons:  $\frac{D_n}{\mu_n} = \frac{kT}{q}$ , holes:  $\frac{D_p}{\mu_p} = \frac{kT}{q}$ 

band to band recombination gives off light, band to band generation through thermal and light absorption, RG center is indirectmiddle step

auger recombination, electron drops, and gives another electron KE. Impact ionization, on a slope, electron moves and falls SI is mostly RG recombination due to impurities

direct semiconductors: k is matched so with less energy there's a photon. With a difference in k, more energy, phonon.

RG statistics:

if photon energy hv is greater than band gap  $E_G$ , iti's absorbed and an electron is moved up.

absorption:  $I = I_0 e^{-\alpha x}$ , each photon creates an e-h pair.  $\frac{dn}{dt}|_{light} = \frac{dp}{dt}|_{light} = G_L(x,\lambda) = G_{L0}e^{-\alpha x}$ 

 $\alpha$  drops off with wavelength. Higher wavelength, lower frequency, lower energy, doesn't get absorbed

indirect thermal recombination-generation,  $n_0, p_0$  under thermal equilibrium, n, p as functions of t.

 $\Delta n = n - n_0$ ,  $\Delta p = p - p_0$ ,  $\Delta$ 's are deviations from equilibrium.  $N_t$  is number of RG centers/cm<sup>3</sup>

low level injection condition assumed, change in majority carrier concentration negligable,  $\Delta p << n_0$ ,  $n \approx n_0$ 

 $\frac{dp}{dt}=\frac{dp}{dt}|_R+\frac{dp}{dt}|_G+G_L(x,\lambda)$ , hole build up = recomb loss + gen gain + external light  $\frac{dp}{dt}|_R=-C_pN_tp$ 

thermal equilibrium:  $\frac{dp}{dt}|_G = -\frac{dp}{dt}|_R = C_p N_t p_0$  generally when  $G_L = 0$ ,  $\frac{dp}{dt} = -\frac{\Delta p}{\tau_p}$ , minority carrier lifetime  $\tau_p = \frac{1}{C_p N_t}$ 

perturbation removed at t=0:  $\Delta p = \Delta p(0)e^{-t/\tau_p}$ 

 $\frac{dp}{dt} = fracdpdt|_{drift} + \frac{dp}{dt}|_{diff} + \frac{dp}{dt}|_{thermalRG} + \frac{dp}{dt}|_{light/other}$  current input: holes:  $\frac{dp}{dt} = \frac{1}{q}\frac{dJ_p}{dx} + \frac{dp}{dt}|_{thermalRG} + \frac{dp}{dt}|_{light/other}$ , electrons: first term is positive Minority carrier diffusion equiations: electrons for p type, simplifications

 $J_n = q\mu_n nE + qD_n \frac{dn}{dx} \approx q\bar{D}_n \frac{dn}{dx}$  $\frac{dn}{dx} = \frac{d}{dx}(n_0 + \Delta n) = \frac{d\Delta n}{dx}$ 

```
\begin{split} \frac{dn}{dt}|_{thermalRG} &= -\frac{\Delta n}{\tau_n} \;,\; \frac{dn}{dt}|_{light} = G_L \\ \frac{dn}{dt} &= \frac{d}{dt}(n_0 + \Delta n) = \frac{d\Delta n}{dt} \\ \frac{d\Delta n_p}{dt} &= D_n \frac{d^2 \Delta n_p}{dx^2} - \frac{\Delta n_p}{\tau_n} + G_L \\ \frac{d\Delta p_n}{dt} &= D_p \frac{d^2 \Delta p_n}{dx^2} - \frac{\Delta p_n}{\tau_p} + G_L \end{split}
Minority carrier diffusion length: L_p = (D_p \tau_p)^{1/2}, average distance minority carriers can diffuse
low level injection assumption, majority carriers don't change significantly
p+ n- is forward biased
L_p is minority p, so n side NEW PAGE Microelectronics Technology S 2024 Crib Sheet Exam 1+2 Hayden Fuller
Equilibrium energy band diagram for pn junction kT/q=.0256V n=n_ie^{(E_F-E_i)/kT}, p=n_ie^{(E_i-E_F)/kT}, E_F low for p, high for n
V = (E_{ref} - E_C)/q, E_{ref} - E_C = qV, E = 1/q dE_C/dx = 1/q dE_i/dx, \rho/\epsilon = dE/dx, \epsilon = K_s \epsilon_0
conceptual pn junction formation
p gives some positive to n and n gives some electrons to p, creating negative region in p and positive region in n
Built in voltage V_{bi}, after formation net drift and diffusion currents sum to zero
E field from nN_D to pN_A, V_{bi}=1/q[(E_i-E_F)_p+(E_F-E_i)_n]=kT/q\ln(p_pn_n/n_i^2)
(E_i - E_F)_p = kT \ln(p/n_i), (E_F - E_i)_n = kT \ln(n/n_i), p_p/p_n = n_n/n_p = e^{V_{bi}q/kT}
Depletion approximation
Poisson dE/dx = \rho/(K_s \epsilon_0) = q/(K_s \epsilon_0)(N_D - N_A) for -x_p < x < x_n, 0 elsewhere
Quantitative analysis: E field
dE/dx = \rho/\epsilon = -qN_A/\epsilon = qN_D/\epsilon
E(x) = \{-qN_A(x_p + x)/\epsilon\} - x_p < x < 0, \{-qN_D(x_n - x)/\epsilon\}0 < x < x_n, 0x < --x_p, x > x_n\}
Relationship between x_n and x_p
E_{max} = -qN_Ax_p/\epsilon = -qN_Dx_n/\epsilon, N_Ax_p = N_Dx_n (equal net charge)
W=x_n+x_p , x_n=WN_A/(N_A+N_D) , x_p=WN_D/(N_A+N_D) , if N_A>>N_D then W\approx x_n , viceversa E=-dV/dx , V_{bi}=-\int_{-xp}^{xn}E(x)dx=N_Dx_nWq/(2\epsilon)=W^2qN_AN_D/(2\epsilon(N_A+N_D))
W = \sqrt{V_{bi}2\epsilon(N_A + N_D)/(qN_AN_D)} = \sqrt{2\epsilon(N_A + N_D)(V_{bi} - V_A)/(qN_AN_D)}
Drift due to E field n to p, holes to p, constant. Diffusion due to added minority carriers, holes to n. E
V_A = 0, med E field, med diffusion currents. V_A > 0, small E, large diff. V_A < 0, large E, small diff
V_A breaks E_F, + to p, smaller gap, p side lowers, n side raises
V_A up linear, E_i gap down linear, carrier concentration exp dec, diffusion current incr exp with V_A
drift constant because limited by how often, not how fast
\mathrm{net} = I_{diff} - I_{drift} \; . \; \; V_A = 0 \quad I_{diff} = I_{drift} = I_0 \; . \; \; I = I_0 e^{V_A/V_{ref}} - I_{drift} = I_0 (e^{V_A/V_{ref}} - 1)
carrier concentrations under equilibrium, carrier_{side}. p side minority electron n_p p_p/p_n = e^{(V_{bi}-V_A)q/kT}, low level injection p_n = p_{n0}e^{V_Aq/kT}, n_p = n_{p0}e^{V_Aq/kT}
minority carrier concentration under bias graph
p side has n_{p0}, slopes up into n_p = n_{p0} + \Delta n_p(x'') for total \Delta n_p(0), \Delta n_p(x'') = \Delta n_p(0)e^{-x''/L_n}
 \Delta p_n(x_n) = p_n(x_n - p_{n0}) = p_{n0}(e^{V_Aq/kT} - 1), \Delta n_p(-x_p) = n_{p0}(e^{V_Aq/kT} - 1)
carrier injection under forward bias
x" axis \Delta n_p(0) = n_{p0}(e^{V_A q/kT} - 1), \Delta n_p(x'') = \Delta n_p(0)e^{-x''/L_p}
x' axis \Delta p_n(0) = p_{n0}(e^{V_A q/kT} - 1), \Delta p_n(x') = \Delta p_n(0)e^{-x'/L_p}
Current and minority carrier diffusion
J_p(x) = qp\mu_p E - qD_p dp/dx, J_n(x) = qn\mu_n E - qD_n dn/dx, simplified J_p(x) = -qD_p dp/dx
\begin{split} &\delta\Delta p/\delta t = D_p \delta^2 \Delta p/\delta x^2 - \Delta p/\tau_p + G_L \;,\; \delta\Delta n/\delta t = D_n \delta^2 \Delta n/\delta x^2 - \Delta n/\tau_n + G_L \;,\; \text{simplified} \;\; 0 = D_p \delta^2 \Delta p/\delta x^2 - \Delta p/\delta x^2 - \Delta p/\tau_p \\ &\text{diode:} \;\; J_p(x'=0) = \Delta p_n(0)qD_p/L_p = p_{n0}qD_p/L_p(e^{V_Aq/kT}-1) \;\; \text{and} \;\; J_n(x''=0) = -n_{p0}qD_n/L_n(e^{V_Aq/kT}-1) \\ &\text{for total current} \;\; J = J_0(e^{V_Aq/kT}-1) = (p_{n0}qD_p/L_p + n_{p0}qD_n/L_n)(e^{V_Aq/kT}-1) \\ &\text{large forward} \;\; V_A >> kT/q \;,\; J = J_0e^{V_Aq/kT} \;.\;\; \text{Large reverse} \;\; V_A << -kT/q \;,\; J = -J_0 \end{split}
Avalanching, Zener, RG current, if V_A approaches V_b i, high current. Series current, high level injection
IV Reverse- Breakdown to G-R part
IV Forward- G-R part(1/2kT) to Ideal(q/kT) to High Level Injection to Series Resistance Effect
reverse breakdown: V_{BR} \propto 1/N_B, V_{BR} is breakdown voltage, N_B is bulk doping on lightly doped side
Avalanching: lightly doped diodes, diff current flips direction, impact ionization, one e from p to n creates more
Electric field must hit critical E_{CR}. steep fall, multiplication factor M = 1/[1 - (|V_A|/V_{BR})^m], m 3 to 6
E(x=0) = -qN_Dx_n/\epsilon_{Si} = -\sqrt{(V_{bi} - V_A)2qN_AN_D/[\epsilon_{Si}(N_A + N_D)]}
Breakdown when E(0) = E_{CR}, \sqrt{V_{BR} 2q N_A N_D / [\epsilon_{Si}(N_A + N_D)]}
Zener: tunneling, wall becomes thin when tall,
I_{R-G} increases with depletion layer volume W increases with reverse voltage.
I_{R-G} = -qAn_iW/2\tau_0 where \tau = (\tau_p + \tau_n)/2 in forward bias: I_{R-G} = I_0'(e^{V_Aq/2kT} - 1), total forward current = I_{diff} + I_{R-G}, I_{diff} = I_0(e^{V_Aq/kt} - 1) where I_0 = qA(D_n + 1)
```

```
since I_{diff} \propto n_i^2 grows faster than I_{R-G} \propto n_i, RG is negligable in forward bias, more ideal in Ge and high temp V_A approaches V_{bi}, I \approx I_0 e^{(V_A - IR_s)q/kt}
log(I) vs V_A is slope q/kT but veers right by \Delta V. \Delta V vs I gives linear slope R_s
High level injection: when V_A within 0.2V ish of V_{bi}, I = e^{V_A q/2kT}, minority hits majority and they increase linearly together
log(I) vs V_A shikanes with Avalanch/Zener breakdown, thermal gen in depletion, origin, thermal recombonation in depletion, ideal
q/kT in middle, high level injection q/2kT above, serries resistance above
Small signal admittance Y=i/v_a=G+j\omega C, res RS to cap CD+ cap DJ + res GD
C_j = \epsilon_{Si}A/W = A\sqrt{\epsilon_{Si}qN_B/2(V_{bi}-V_A)}, up with \sqrt{N_B}, down with reverse bias
W = \sqrt{2\epsilon_{Si}(N_A + N_D)(V_{bi} - V_A)/(qN_AN_D)} = \sqrt{2\epsilon_{Si}(V_{bi} - V_A)/(qN_B)}
1/C_J^2 = 2(V_{bi} - V_A)/(A^2qN_B\epsilon_{Si}), vs V_A, slope first part, = 0 at V_{bi}
C_D charge storage cap dominant in forward bias. p+n has I=Q_p/\tau_p where Q_p total excess charge n side
Q_p = I\tau_p = qAD_p\tau_p p_{n0}/L_p * [e^{V_Aq/kT} - 1] \approx qAL_p p_{n0}e^{V_Aq/kT}
C_D = dQ_p/dV = I\tau_p q/kT, G_D = Iq/kT
Transient response, charge Q_p goes zero when turned off from current flow and recomb, dQ_p/dt = i(t) - Q_p/\tau_p
Q_p = qAL_p\Delta p_n(0), to maintain charge, current I = qAL_p\Delta p_n(0)/\tau_p must be supplied at x' = 0
Q_p(t) = I\tau_p e^{-t/\tau_p}, \ I_F = V_F - V_{on}/R_F \approx V_F/R_F, \ I_R = V_R + v_A(t)/R_R \approx V_R/R_R
charge between reverse and forward curves needs to be moved, drop over time is pulled from axis
storage delay time: dQ_p/dt = i - Q_p/\tau_p = -I_R - Q_p/\tau_p for 0 < t < t_s, t_s = \tau_p \ln(1 + I_F/I_R)
applications: rectifiers, low R in forward, p+n + preferred, reduce parasitic resistance, low I_0 in reverse, High voltage breakdown,
p+nn+high band gap materials
switching, fast, dope with gold to reduce lifetimes, narrow base for small stored charge
Zener, heavy dope p+ and n+ for low breakdown, reference voltage
Varactor, variable resistance, V controlled C for tuning radio or TV, C_J \propto V_A^{-1}/2 (abrupt, dope to linear)
Opto-elect, photodetect, solar cells, LED, laser diodes. PhotoD: I_L = -qAG_L(L_N + W + L_P), I = I_{dark} + I_L
BJT: pnp: IE in IB+IC out. npn: IB+IC in, IE out
biasing modes: B is expected to be - for pnp, Mode, EB polarity, CB polarity. Saturation, F, F. ACTIVE, F, R. Inverted, R, F.
Cutoff, R, R. A S
n C I. Vert+ VEB pnp VBE npn. Horiz+ VCB pnp VBC npn
electrostatic equilibrium p+ n p EBC,
V = -1/q(E_C - E_{ref}), up and flatens in B, drops to flat in C
E = 1/qdE_C/dx = 1/qdE_i/dx, sharp negative triangle left B, smaller positive left C
dE/dx = \rho/\epsilon
forward, p+ thinB n, small E to p+, big h/e and small e/h, same thinB small E, minority e lower than minority h, both going up
reverse, n wideB p, large E to p, e/h and h/e, minorities drop off to 0
combine for p+ n p, curve up to thin, curve down and drop to wide, up to e
make B very thin, curve up to thin, drop to zero for rev bias, back up a bit, D and CS I = \alpha I_E, B has I = (1 - \alpha)I_E
emitter efficiency \gamma = I_{EP}/(I_{EP} + I_{EN}) = I_{EP}/I_E
base transport factor \alpha_T = I_C/I_{Ep}
I_C = \alpha_T I_{EP} = \alpha_T \gamma I_E = \alpha_{dc} I_E , \ \alpha_{dc} = \alpha_T \gamma
I_C = \beta_{dc}I_B, \beta_{dc} = \alpha_{dc}/(1 - \alpha_{dc}) = \alpha_T\gamma/(1 - \alpha_T\gamma)
detailed quantitative analysis, assume pnp, steady state, low level, only drift and diff, no gen, one dimension, etc.
solve minority carrier diffusion equations for each of the three regions
\delta \Delta p/\delta t = D_p \delta^2 \Delta p/\delta x^2 - \Delta p/\tau_p + G_L, \ \delta \Delta n/\delta t = D_n \delta^2 \Delta n/\delta x^2 - \Delta n/\tau_n + G_L
under steady state G_L = 0, 0 = D_p \delta^2 \Delta p / \delta x^2 - \Delta p / \tau_p, 0 = D_n \delta^2 \Delta n / \delta x^2 - \Delta n / \tau_n
for pnp base, only interested in holes (current in E and split)
\Delta n = n - n_0 excess carriers above equilibrium, area of excess carriers = Q_n.
X_B and X_E flow away
from BE junction, I_E = I_P - I_N \approx (qAp_{B0}D_B/L_B*e^{V_{EB}q/kT}) + (qAn_{E0}D_E/L_E*e^{V_{EB}q/kT})
I_P = Q_p/	au_B, I_P = Q_n/	au_E. n_E curve up, p_B linear down, n_C collecter curve up
I_E broken down into I_n = qaD_n dn/dx and I_p = -qAD_p dp/dx
I_C = qAD_B p_B(0)/W_B = qAp_{B0}D_B/W_B * e^{V_{EB}q/kT}
I_E made up of I_{EP} and I_{EN}
I_{EP} = I_c + qAW_B\Delta p_B(0)/2\tau_B \approx qAp_{B0}D_B/W_Be^{V_{EB}q/kT} + qAp_{B0}W_B/2\tau_Be^{V_{EB}q/kT}
I_B = qAp_{B0}W_B/2\tau_B e^{V_{EB}q/kT} + qAn_{E0}D_E/L_E e^{V_{EB}q/kT} (recombination + e injection to E)
\alpha_T = 1/[1 + (W_B/L_B)^2/2], \ \gamma = 1/[1 + D_E n_{E0} W_B/D_B p_{B0} L_E] = 1/[1 + D_E W_B N_B/D_B L_E N_E]
BJT in cutoff, minority carriers drop off on E and C, zero in B.
BJT in saturation, E and C curve up, p_{B0} is linear down but still high, above E below C.
Base width modulation I_C \approx qAD_B\Delta p_B(0)/W_Be^{V_{EB}q/kT}, B drops to 0 at C
Early effect, CB reverse bias up, depletion width up, W down, I_C up
punch through, W approaches 0. for high reverse CB, EB barrier lowers, and large I_C at high V_{CE0} due to either punchthrough
or avalanch
```

 $n_i^2/L_n N_A + D_p n_i^2/L_p N_D)$